Title (en)

METHOD AND DEVICE FOR ELECTRICALLY CONTACTING A MATERIAL SURFACE WHICH IS COATED WITH AT LEAST ONE DIELECTRIC LAYER

Title (de)

VERFAHREN SOWIE EINE VORRICHTUNG ZUR ELEKTRISCHEN KONTAKTIERUNG EINER MIT WENIGSTENS EINER DIELEKTRISCHEN SCHICHT ÜBERZOGENEN MATERIALOBERFLÄCHE

Title (fr)

PROCEDE ET DISPOSITIF DE MISE EN CONTACT ELECTRIQUE D'UNE SURFACE DE MATERIAU RECOUVERTE D'AU MOINS UNE COUCHE DE DIELECTRIQUE

Publication

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Application

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Abstract (en)

[origin: DE19915666A1] The invention relates to a method and a device for electrically contacting a material surface which is coated with at least one dielectric layer. The invention is characterised in that light from a light source is directed onto an arrangement consisting of a number of optical microlenses that are arranged in an array and through which the light is directed onto the dielectric layer; and in that a liquid or viscous medium is introduced between the arrangement consisting of the number of optical microlenses that are arranged in an array and the dielectric layer. This layer is essentially transparent to the light of the light source and material is removed locally from the dielectric layer through the specific illumination thereof until the material surface is exposed locally, respectively. The invention is also characterised in that metallisation takes place through the dielectric layer at the points where the material surface has been locally exposed, starting from the material surface.

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